

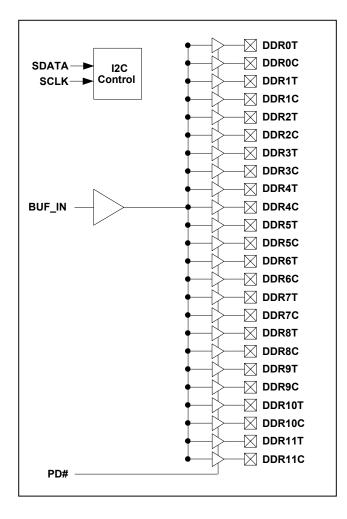
PLL103-02

DDR SDRAM Buffer for Desktop PCs with 4 DDR DIMMS

FEATURES

- Generates 24 output buffers from one input.
- Supports up to four DDR DIMMS.
- Supports 266MHz DDR SDRAM.
- One additional output for feedback.
- Less than 5ns delay.
- Skew between any outputs is less than 100 ps.
- 2.5V Supply range.
- Enhanced DDR Output Drive selected by I2C.
- Available in 48 pin SSOP.

BLOCK DIAGRAM



PIN CONFIGURATION

				1
FBOUT 🖂	1	\bigcirc	48	□ N/C
VDD2.5 🖂	2		47	UDD2.5
GND 🗆	3		46	
DDR0T	4		45	DDR11T
DDR0C	5		44	DDR11C
DDR1T	6		43	DDR10T
DDR1C	7		42	DDR10C
VDD2.5 🖂	8		41	UDD2.5
GND 🗆	9		40	🗖 GND
DDR2T	10	P	39	DDR9T
DDR2C	11		38	DDR9C
VDD2.5	12	Z	37	UDD2.5
BUF_IN	13	2	36	D PD#
GND 🖂	14	03	35	
DDR3T 🖂	15	, w	34	DDR8T
DDR3C	16	6	33	DDR8C
VDD2.5	17	N	32	UDD2.5
GND 🗆	18		31	
DDR4T	19		30	DDR7T
DDR4C	20		29	DDR7C
DDR5T 🖂	21		28	DDR6T
DDR5C	22		27	DDR6C
VDD2.5	23		26	🗆 GND
SDATA 🖂	24		25	SCLK
				1

Note: #: Active Low

DESCRIPTION

The PLL103-02 is designed as a 2.5V buffer to distribute high-speed clocks in PC applications. The device has 24 outputs. These outputs can be configured to support four unbuffered DDR DIMMS. The PLL103-02 can be used in conjunction with a clock synthesizer for the VIA Pro 266 chipset. The PLL103-02 also has an I2C interface, which can enable or disable each output clock. When powered up, all output clocks are enabled (have internal pull ups).



PIN DESCRIPTIONS

Name	Number	Туре	Description
FBOUT	1	0	Feedback clock for chipset.
BUF_IN	13	I	Reference input from chipset.
PD	36	I	Power Down Control input. When low, it will tri-state all outputs.
N/C	48		Not connected.
DDR[0:11]T	4,6,10,15,19, 21,28,30,34, 39,43,45	0	These outputs provide True copies of BUF_IN.
DDR[0:11]C	5,7,11,16,20, 22,27,29,33, 38,42,44	0	These outputs provide complementary copies of BUF_IN.
VDD2.5	2,8,12,17,23, 32,37,41,47	Р	2.5V power supply.
GND	3,9,14,18,26, 31,35,40,46	Р	Ground.



I2C BUS CONFIGURATION SETTING

Address Assignment	A6 1	A5 1	A4 0	A3 1	A2 0	A1 0	A0 1	R/W		
Slave Receiver/Transmitter	Provid	des both s	lave write	and readb	oack functi	onality				
Data Transfer Rate	Stand	tandard mode at 100kbits/s								
Data Protocol	bytes must termir addre Follov Coun	must be a be followe hate the trans ss and a w ving the ac t Byte mu	ccessed i d by 1 ack ansfer. Th vrite cond cknowledg st be sen be read l	n sequenti knowledge e write or ition (0xD2 je of this a t by the n	ial order fr bit. A byte read block 2) or a read ddress by naster but	om lowest e transferr c both beg d conditior te, in Writ ignored b	to highest ed without ins with the n (0xD3). e Mode: th y the slave	acknowledge e master sene e Command , in Read Mo	oyte transferred ed bit will	

I2C CONTROL REGISTERS

1. BYTE 6: Outputs Register (1=Enable, 0=Disable)

Bit	Pin#	Default	Description
Bit 7	48	1	Reserved
Bit 6	-	0	Reserved
Bit 5	-	0	Enhanced DDR Drive. 1 = Enhanced 25%
Bit 4	-	0	Reserved
Bit 3	45, 44	1	DDR11T, DDR11C
Bit 2	43, 42	1	DDR10T, DDR10C
Bit 1	39, 38	1	DDR9T, DDR9C
Bit 0	34, 33	1	DDR8T, DDR8C

2. BYTE 7: Outputs Register (1=Enable, 0=Disable)

Bit	Pin#	Default	Description
Bit 7	30, 29	1	DDR7T, DDR7C
Bit 6	28, 27	1	DDR6T, DDR6C
Bit 5	21, 22	1	DDR5T, DDR5C
Bit 4	19, 20	1	DDR4T, DDR4C
Bit 3	15, 16	1	DDR3T, DDR3C
Bit 2	10, 11	1	DDR2T, DDR2C
Bit 1	6, 7	1	DDR1T, DDR1C
Bit 0	4, 5	1	DDR0T, DDR0C



ELECTRICAL SPECIFICATIONS

1. Absolute Maximum Ratings

PARAMETERS	SYMBOL	MIN.	MAX.	UNITS
Supply Voltage	Vdd		4.6	V
Input Voltage, dc	V ₁	V _{SS} -0.5	V_{DD} +0.5	V
Output Voltage, dc	Vo	Vss-0.5	V _{DD} +0.5	V
Storage Temperature	Ts	-65	150	°C
Ambient Operating Temperature*	TA	-40	85	°C
Junction Temperature	TJ		125	°C
Lead Temperature (soldering, 10s)			260	°C
ESD Protection, Human Body Model			2	kV

Exposure of the device under conditions beyond the limits specified by Maximum Ratings for extended periods may cause permanent damage to the device and affect product reliability. These conditions represent a stress rating only, and functional operations of the device at these or any other conditions above the operational limits noted in this specification is not implied.

* Note: Operating Temperature is guaranteed by design for all parts (COMMERCIAL and INDUSTRIAL), but tested for COMMERCIAL grade only.

2. Operating Conditions

PARAMETERS	SYMBOL	MIN.	MAX.	UNITS
Supply Voltage	V _{DD2.5}	2.375	2.625	V
Input Capacitance	CIN		5	pF
Output Capacitance	Соит		6	pF

3. Electrical Specifications

PARAMETERS	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Input High Voltage	VIH	All Inputs except I2C	2.0		V _{DD} +0.3	V
Input Low Voltage	VIL	All inputs except I2C	Vss-0.3		0.8	V
Input High Current	Іін	$V_{IN} = V_{DD}$			TBM	uA
Input Low Current	IIL	V _{IN} = 0			TBM	uA
Output High Voltage	V _{OH}	IOL = -12mA, VDD = 2.375V	1.7			V
Output Low Voltage	Vol	IOL = 12mA, VDD = 2.375V			0.6	V
Output High Current	Іон	VDD = 2.375V, VOUT=1V	-18	-32		mA
Output Low Current	lol	VDD = 2.375V, VOUT=1.2V	26	35		mA

Note: TBM: To be measured



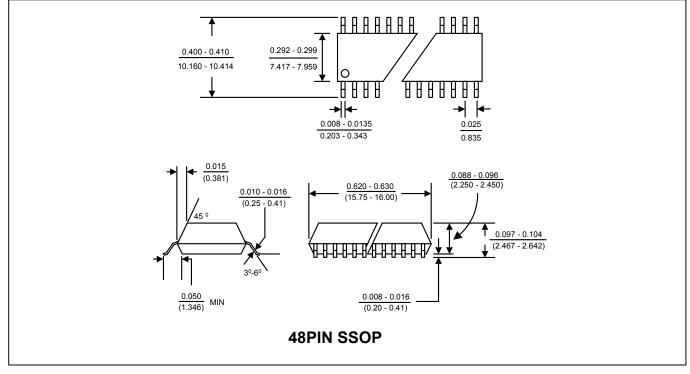
3. Electrical Specifications (Continued)

PARAMETERS	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Supply Current	I _{DDS}	PD = 0			TBM	mA
Output Crossing Voltage	Voc		(VDD/2) -0.1	VDD/2	(VDD/2)+ 0.1	V
Output Voltage Swing	Vouт		1.1		VDD-0.4	V
Duty Cycle	DT	Measured @ 1.5V	45	50	55	%
Max. Operating Frequency			66		170	MHz
Rising Edge Rate	Tor	Measured @ 0.4V ~ 2.4V	1.0	1.5	2.0	V/ns
Falling Edge Rate	Tof	Measured @ 2.4V ~ 0.4V	1.0	1.5	2.0	V/ns
Clock Skew(pin to pin)	Тѕкеѡ	All outputs equally loaded			100	ps
Stabilization Time	T _{ST}				0.1	ms

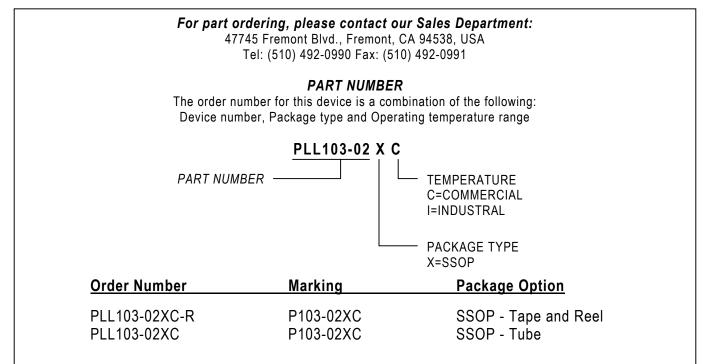
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